

**Energy efficient**  
from Cloud to the Edge

**10.24 ONLY**



**Lucky Draw & Ice Cream Party  
Only on the 24th!**

INVITED BY \_\_\_\_\_ BOOTH NO. \_\_\_\_\_

# INVITATION



**2025 OCT. 22 WED-24 FRI.**  
TaiNEX 1, TAIPEI 1F, 4F  
**10:00 – 17:00** ( Final Day 15:00 )

## Special Exhibition

| End Applications                                                                                                                                                    | AI and intelligent manufacturing applications                                                                                            | Thermal management and thermal imaging applications                                                                                                   | Advanced Processes and Advanced Packaging                                                                    |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------|
| <ul style="list-style-type: none"> <li>Computing</li> <li>Communication</li> <li>Automotive</li> <li>Aerospace and Defense</li> <li>Consumer Electronics</li> </ul> | <ul style="list-style-type: none"> <li>AI package inspection</li> <li>AI software development</li> <li>Edge AI</li> <li>Robot</li> </ul> | <ul style="list-style-type: none"> <li>Infrared sensor process</li> <li>Module packaging</li> <li>Optical systems and product applications</li> </ul> | <ul style="list-style-type: none"> <li>CoWos , CoPos</li> <li>FOPLP</li> <li>TGV &amp; Glass Core</li> </ul> |
|                                                                                                                                                                     |                                                                                                                                          |                                                                                                                                                       |                                                                                                              |

all exhibitors are on [www.tpcashow.com](http://www.tpcashow.com)

全球電子產業正在加速跨界融合，從PCB、SMT、載板到高階封裝與半導體製程，規模再創歷史新高，逾670+國際品牌、1750個攤位，TPCA Show正是您一站式掌握供應鏈最新技術、材料與夥伴的最佳平台。我們誠摯邀請您於2025年10月22日至24日親臨台北南港展覽館一館，與來自全球的技術專家、創新企業及潛在合作夥伴共聚盛會。

TPCA Show is the leading international exhibition bridging the entire value chain from PCBs, SMT, thermal solutions, substrates to advanced packaging and AI-driven manufacturing. Join us in Taipei and explore what's next.

### 9 大主題分區

IC Substrates, Thermal, Green Tech, Automation, etc.



**載板與高階電路板製造本業區**  
IC Substrate & PCBs



**光電專區**  
OPTO Pavillion



**乾、溼製程設備**  
Dry & Wet Process Equipment



**自動化解決方案**  
Automation Equipment



**高質新材料、耗材與化學品**  
Materials & Chemicals



**綠色科技區**  
Green Tech



**SMT/熱管理技術**  
SMT / Thermal Management



**檢測設備與軟體**  
Testing Equipment



**矽光子專區**  
HiSPA Pavillion

更多訊息請至官網 For more information Website : [www.tpcashow.com](http://www.tpcashow.com)

### 活動介紹 Activity

- 開幕典禮暨主題演講《產業領航者的AI供應鏈戰略》  
Opening Ceremony & Keynote: "AI-Driven Supply Chain Strategies by Industry Leaders"
- 產業領袖高峰會 **CEO Summit**：與決策者直接對話
- 半導體與PCB異質整合高峰論壇：  
**Semiconductor X PCB Summit**
- 洞察未來趨勢 **Tech X Total solution**
  - Pack Vision 封裝視界**  
(CoWoS, CoPoS, Packaging, IC Substrates...)
  - Smart Link 智聯製造**  
(AI、IoT、數智製造、機器人、AI檢測與軟體...)
  - Next Core 次世代核心**  
(TGV、Glass Core、FoPLP...)
  - Hyper Edge 高速邊緣**  
(HPC、5G、伺服器、熱管理與應用)
  - Auto Next 車用科技** (EV與車用電子)
  - Green Tech 綠能科技** (永續與淨零)
- 人才原力媒合=電路板 X Z世代人才  
**Digital Talent Match Day**



鼓勵搭乘大眾交通工具，攜手減碳共創環境永續，一起參與綠色看展！  
Take rapid transportation, make this world green.



謝絕18歲以下及非相關行業民眾入場參觀。  
Under 18 not admitted.



**IMPACT** Oct. 21-24  
International Microsystems, Packaging,  
Assembly and Circuits Technology conference



[www.impact.org.tw](http://www.impact.org.tw)